



Appl. No. 10/024,936

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant	:	Joel Wayne Davenport, et al.	:	
Appl. No.	:	10/024,936	:	Grp./Art Unit : 2827
Filed	:	18 December 2001	:	Examiner: L. Cruz
Title	:	Single Package Containing	:	
		Multiple Integrated Circuit Devices;	:	
			:	
Docket No.	:	US018102	:	

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Assistant Commissioner for Patents

**RESPONSE and AMENDMENT**

Sir:

This is in response to the Office Action of 20 March 2003.

**IN THE SPECIFICATION**

Please replace the paragraph beginning at page 5, line 19 with the following:

FIG. 2A shows a perspective view of package 10 having a plurality of solder balls 16, which are used for connecting to one another and to other external devices. FIG. 2B shows a bottom view of package 10. As shown in FIG. 2B, there are two sets of external electrical connection contacts 22 and 24 in the form of solder balls, associated with devices 2 and 4, respectively. Two spacing gaps 26 and 28 separate the two sets of external electrical connection contacts in two sections to maintain electrical isolation between devices 2 and 4. Spacing gaps 26 and 28 are created by removing the external connection contacts in the pre-selected areas. Spacing gaps 26 and 28 are also maintained at the minimum physical widths in accordance with Table 6-1 of the ANSI/IPC-2221 standard described above.

**IN THE CLAIMS**

Please cancel non-elected Claims 8-12 without prejudice or disclaimer.

Please amend Claims 1-3, 5, 13 and 15.

1. (Amended) A ball grid array (BGA) package assembly having a plurality of